

DRDC3105

INTEGRATED RELAY, INDUCTIVE LOAD DRIVER

Description and Applications

The DRDC3105 is an integrated solid-state DC relay driver that can switch inductive loads. It provides a robust driver interface by acting as a buffer stage between sensitive logic circuits and that of 3 to 6V DC inductive relay coils. With a low input drive current requirement, the DRDC3105 only has slight loading on the input circuitry and it will provide good transient isolation between output and input channels. The output switch is guaranteed by design to go open-circuit and fall into the off-state condition when input drive is lost or disconnected.

In the industry standard SOT23 and SOT26, the DRDC3105 comes as a single or dual die which can replace three to six individual discrete components within a single integrated package, including a Zener across the output. The Zener will clamp at 6.6V to sink inductive currents to ground which will reduce EMI noise in the system. By integrating the Zener, the DRDC3105 eliminates the need for an external free-wheeling diode and allows the driving of inductive loads such as relays, solenoids, incandescent lamps, and small DC motors in:

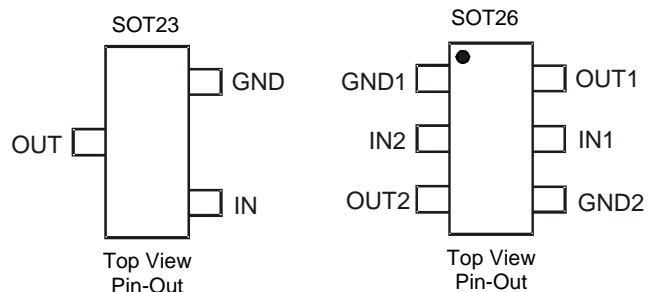
- Automotive: 5.0 V Driven Relays, Lamp Drivers, Motor Controls
- Telecom equipment: Modems, DSL, Cable (EMTA), Line Cards, IP-PBX, Analog Terminal Adaptors, End User Telecom Equipment
- Desktop Computers, Printers, Photocopiers
- LCD & Plasma TVs, Set Top Boxes
- Consumer Appliances, White Goods, Automated Door Control
- Industrial equipment inc. Process Control, ATE equipment
- Solar inverters

Features and Benefits

- Inductive load driver capable of driving 3 to 6V DC coils
- Optimized to switch inductive loads from supply of 3 to 5V with the capability to drive coils up to 2.5W from a 5V rail
- Fully integrated into a single SOT23 or dual SOT26 package to minimize footprint area and reduce number of components
- Includes Zener across output to reduce EMI noise
- Internal low saturation BJT to reduce power dissipation in driving high currents into the coil
- Output guaranteed to be in off-state condition during no input
- Near – Zero quiescent supply current in off-state condition with minimal leakage
- Rugged design and inherently robust by using solid-state BJT technology integrated into a single die
- **ESD Protected up to 1kV on Human Body Model (HBM)**
- **“Lead-Free”, RoHS Compliant (Note 1)**
- **Halogen and Antimony Free “Green” Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT23 & SOT26
- Case material: “Green” plastic molding compound (Note 2)
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: SOT23 = 0.008 grams (Approximate)
SOT26 = 0.018 grams (Approximate)

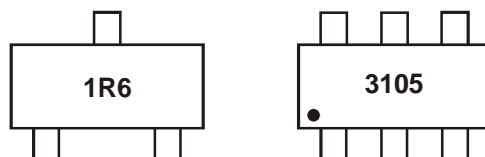


Ordering Information (Note 3)

Product	Package	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DRDC3105F-7	SOT23	1R6	7	8	3,000
DRDC3105E6-7	SOT26	3105	7	8	3,000

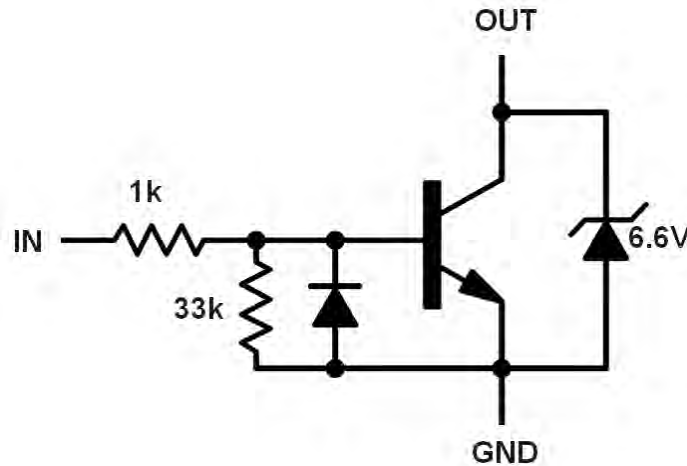
- Notes:
1. No purposefully added lead.
 2. Diodes Inc's "Green" policy can be found on our website at <http://www.diodes.com>
 3. For packaging details, go to our website at <http://www.diodes.com>

Marking Information



1R6 = SOT23, Product type Marking Code
3105 = SOT26, Product type Marking Code

Internal Device Schematic



Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Limit	Unit
Supply Voltage	V _{CC}	6.0	V
Input Voltage (Forward)	V _{in(fwd)}	6.0	V
Input Voltage (Reverse)	V _{in(rev)}	-0.5	V
Output Sink Continuous Current	I _o	500	mA
Repetitive Pulse Zener Energy Limit (Duty Cycle 0.01%)	E _{zpk}	50	mJ

Thermal Characteristics for DRDC3105F (SOT23) @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	330	mW
Linear Derating Factor		2.64	mW/°C
Thermal Resistance, Junction to Ambient	R _{θJA}	379	°C/W
Thermal Resistance, Junction to Case	R _{θJC}	306	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
4. For a device surface mounted on 25mm X 25mm X 1.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air condition; the device is measured when operating in a steady-state condition.
 5. Thermal resistance from junction to case.

Thermal Characteristics for DRDC3105E6 (SOT26) @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	0.9	W mW/°C
		7.2	
		1.1	
		8.8	
Thermal Resistance, Junction to Ambient	R _{θJA}	1.7	°C/W
		13.6	
		139	
Thermal Resistance, Junction to Leads	R _{θJL}	113	°C/W
		73	
		100	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
6. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
 7. For a device surface mounted on FR4 PCB measured at < 5sec
 8. Repetitive rating – pulse width limited by maximum junction temperature. Refer to transient thermal impedance graph
 9. For a device with one active die
 10. For a device with two die running at equal power
 11. Thermal resistance from junction to solder-point (at the end of the "OUT" lead).

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Output Zener Breakdown Voltage	BV _(out) BV _(-out)	6.2 -	6.6 0.67	7.0 -	V	@ IT = 10 mA Pulse
Output Leakage Current @ 0 Input Voltage	I _{OO}	- -	- -	0.1 30	μA	V _O = 5.5 V, T _A = 25°C V _O = 5.5 V, T _A = 85°C
“ON” state input voltage (Note 12)	V _{in(on)}		0.99	1.5	V	I _O = 100 mA, V _O = 150mV
“OFF” State Input Voltage (Note 13)	V _{in(off)}	400	540	-	mV	I _O = 100 μA, V _O = 4.9V
ON CHARACTERISTICS						
Input Bias Current (H _{FE} Limited)	I _{in}	-	0.7	1.6	mA	I _O = 250 mA, V _O = 0.25 V
Output Saturation Voltage	V _{O(sat)}	-	125	160	mV	I _O = 250 mA, I _{in} = 1.5 mA
Output Sink Current – Continuous	I _{O(on)}	250	430	-	mA	V _{CE} = 0.25 V, I _{in} = 1.5 mA
SWITCHING CHARACTERISTICS (Refer to Figure 1)						
Propagation Delay Times:						
High to Low Propagation Delay; (5.0V 74HC04)	t _{PHL}	-	20.4	-	ns	-
Low to High Propagation Delay; (5.0V 74HC04)	t _{PLH}	-	1.43	-	μs	-
High to Low Propagation Delay; 13 (3.0V 74HC04)	t _{PHL}	-	32.2	-	ns	-
Low to High Propagation Delay; 13 (3.0V 74HC04)	t _{PLH}	-	760	-	ns	-
High to Low Propagation Delay; 14 (5.0V 74LS04)	t _{PHL}	-	25.3	-	ns	-
Low to High Propagation Delay; 14 (5.0V 74LS04)	t _{PLH}	-	2.57	-	μs	-
Transition Times:						
Fall Time; (5.0V 74HC04)	t _f	-	12.5	-	ns	-
Rise Time; (5.0V 74HC04)	t _r	-	411	-	ns	-
Fall Time; 13 (3.0V 74HC04)	t _f	-	21.1	-	ns	-
Rise Time; 13 (3.0V 74HC04)	t _r	-	220	-	ns	-
Fall Time; 14 (5.0V 74LS04)	t _f	-	15.1	-	ns	-
Rise Time; 14 (5.0V 74LS04)	t _r	-	849	-	ns	-

Notes: 12. The device is guaranteed to be in “ON” state with V_{in(on)} above 1.5V
13. The device is guaranteed to be in “OFF” state with V_{in(off)} below 400mV

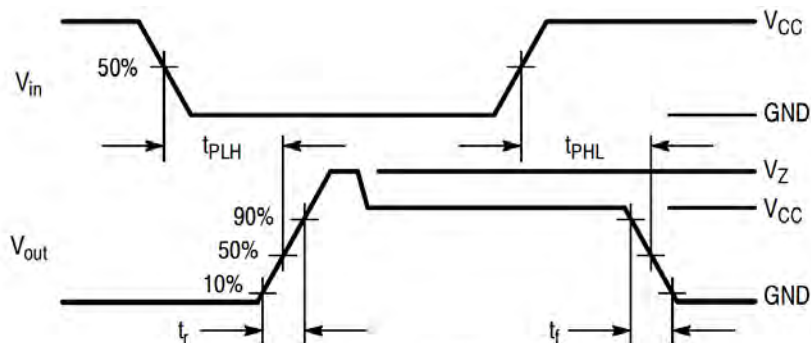


Figure 1. Switching Waveforms

Typical Electrical Characteristics

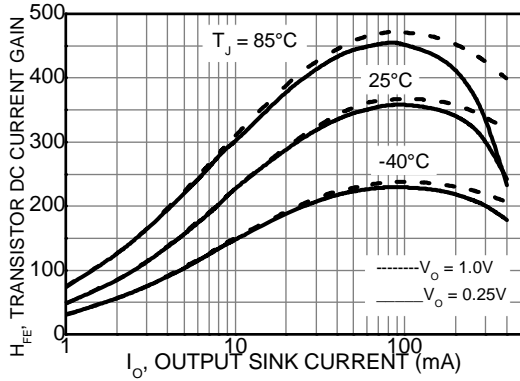


Figure 2. Transistor DC Current Gain

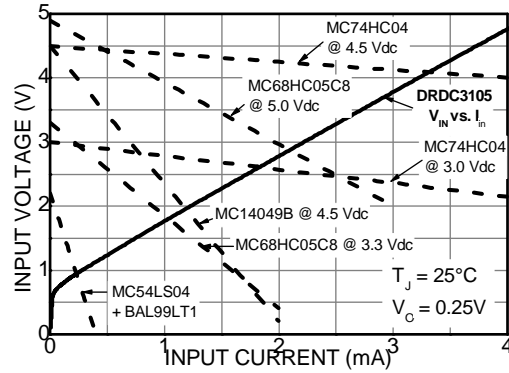


Figure 3. Input V-I Requirement Compared to Possible Source Logic Outputs

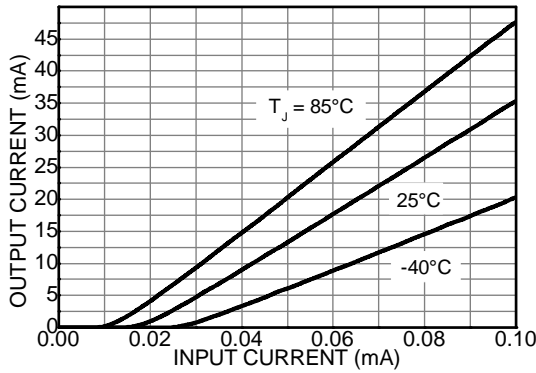


Figure 4. Threshold Effects

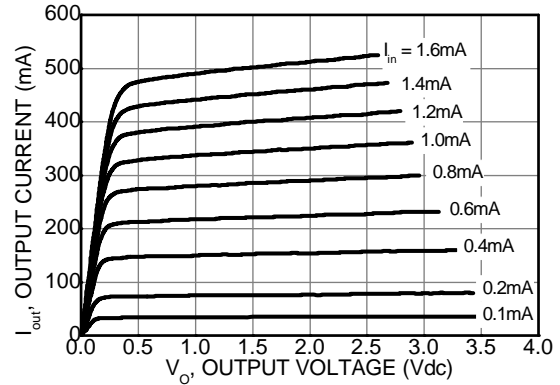


Figure 5. Transistor Output V-I Characteristic

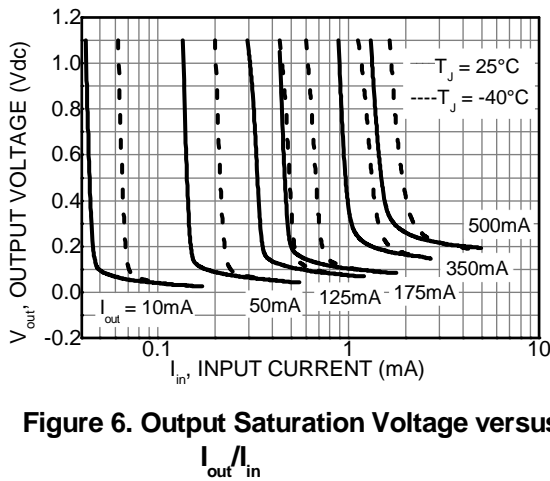


Figure 6. Output Saturation Voltage versus I_{out}/I_{in}

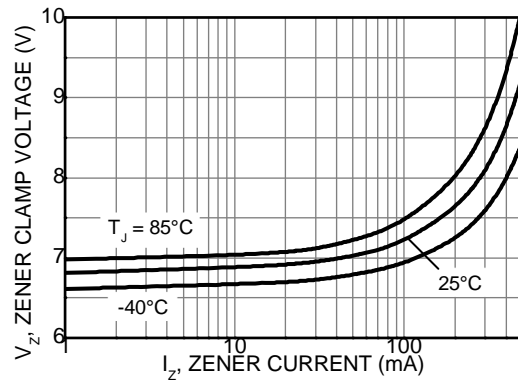


Figure 7. Zener Clamp Voltage versus Zener Current

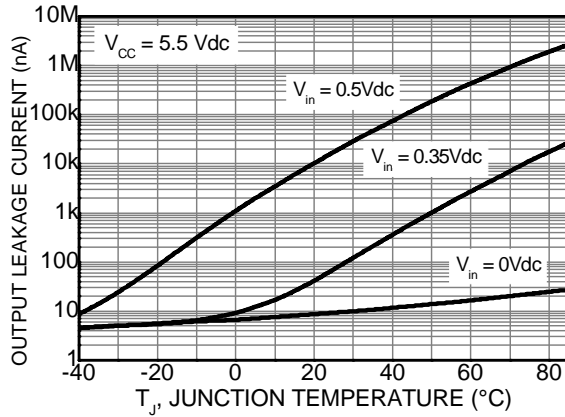


Figure 8. Output Leakage Current versus Temperature

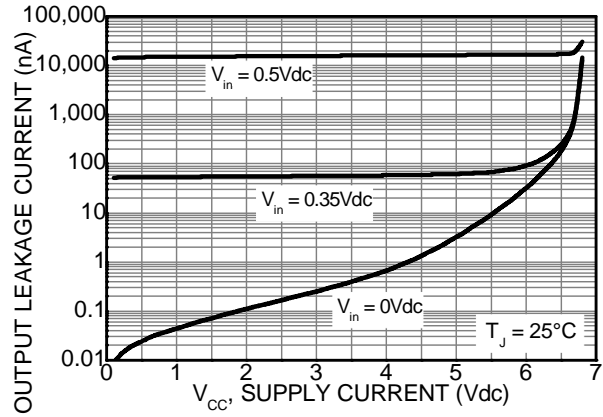


Figure 9. Output Leakage Current versus Supply Voltage

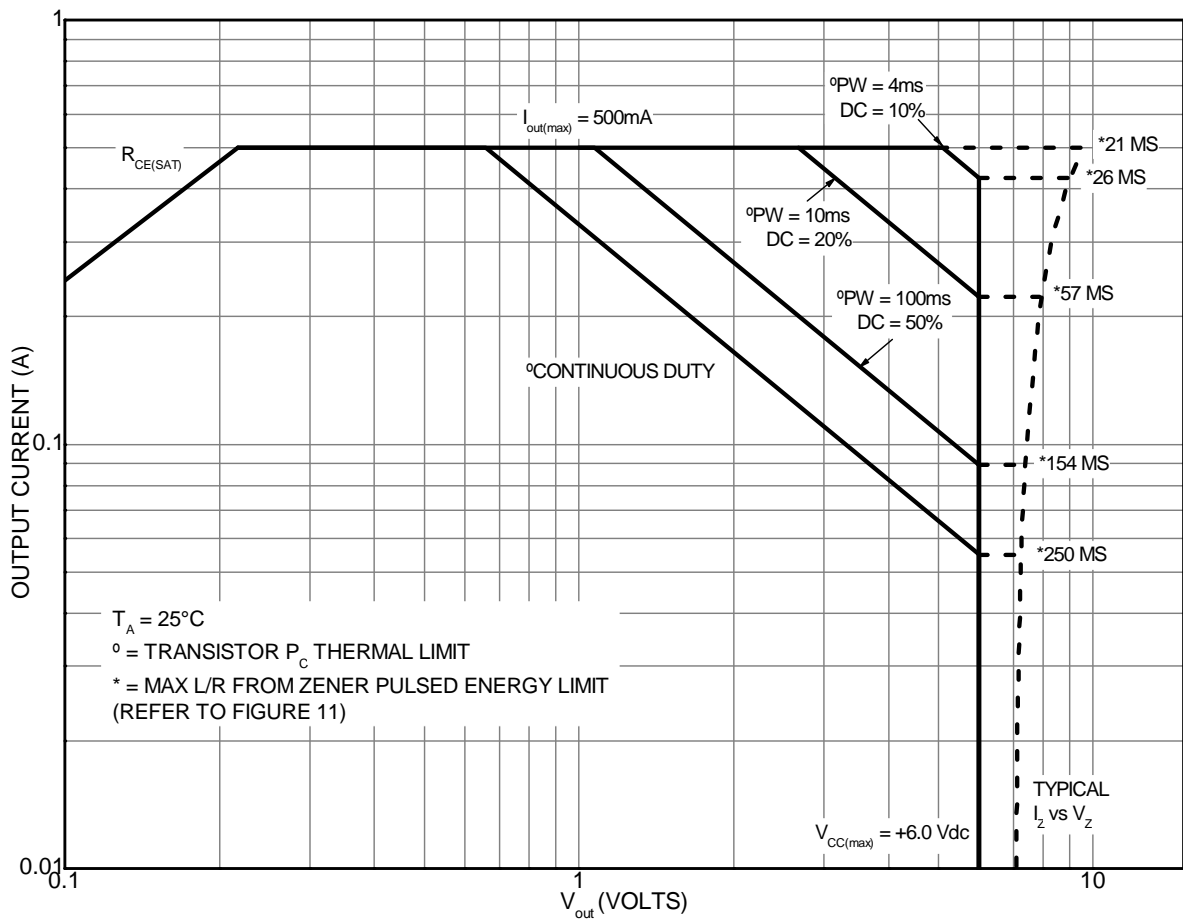


Figure 10. Safe Operating Area

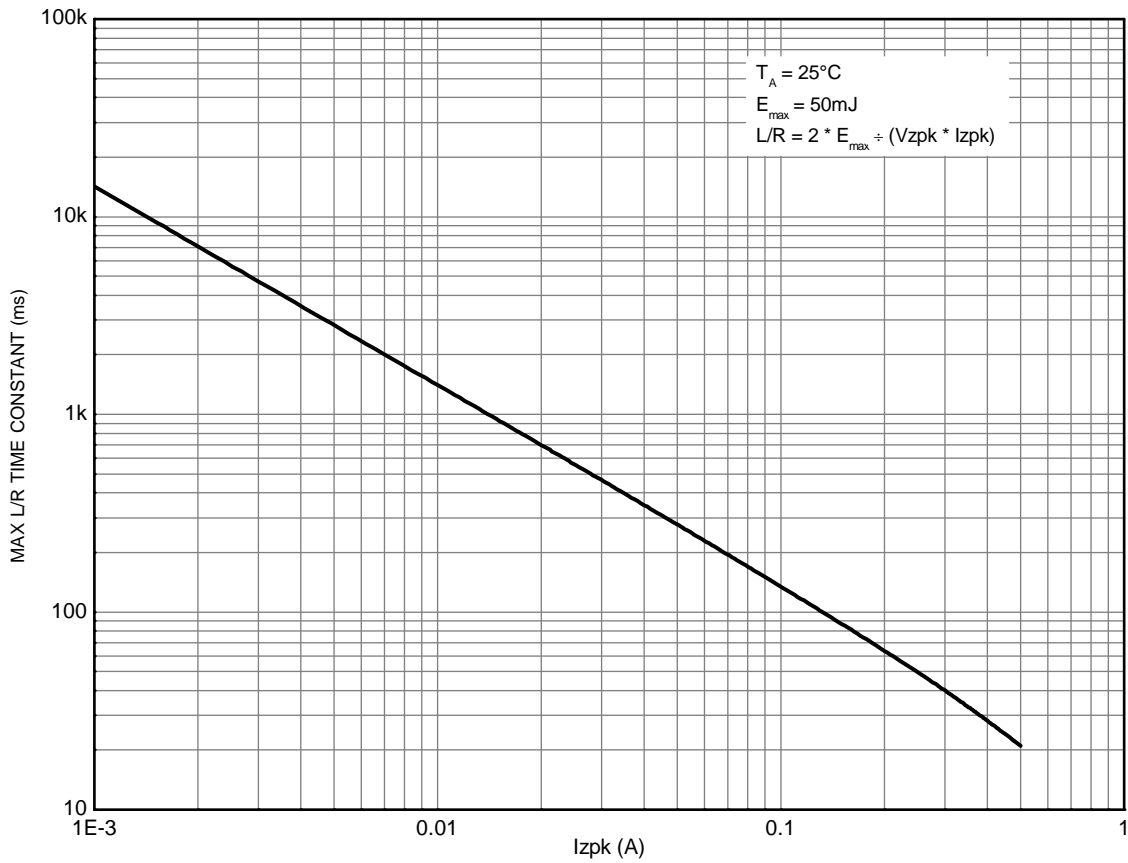


Figure 11. Zener Repetitive Pulse Energy Limit on L/R Time Constant

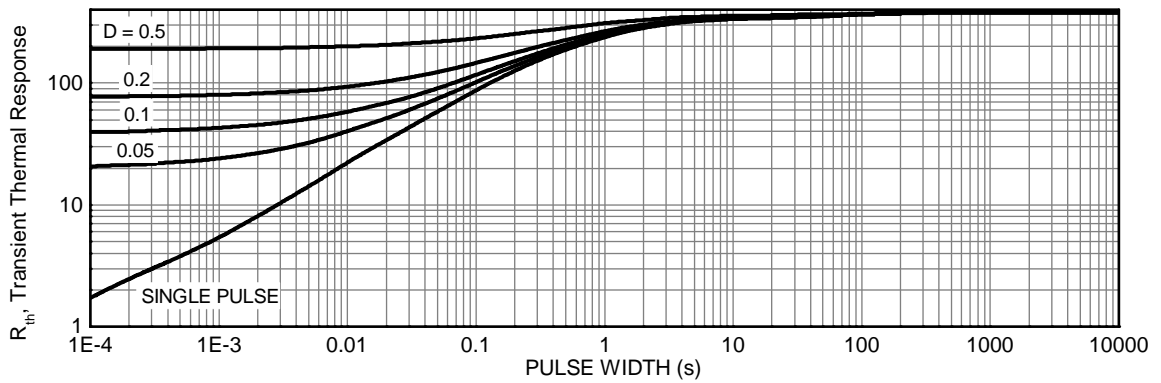
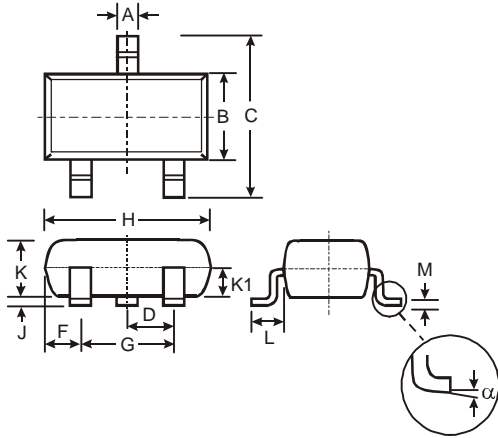


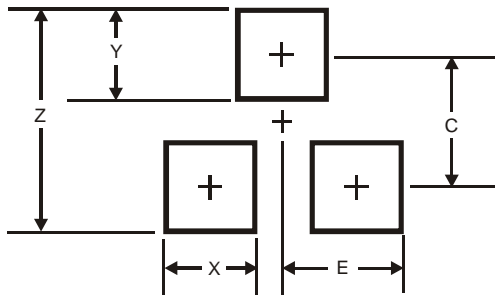
Figure 12. Transient Thermal Response

Package Outline Dimensions for SOT23



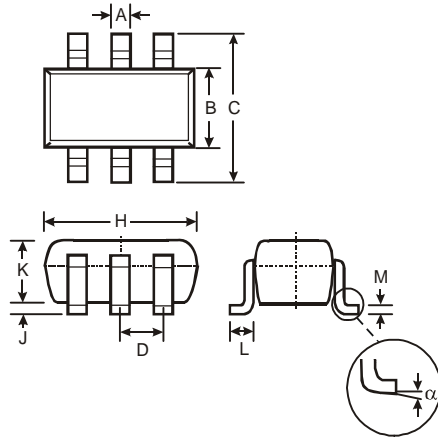
SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout for SOT23



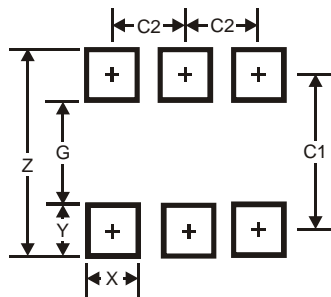
Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Package Outline Dimensions SOT26



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout for SOT26



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

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